

1 **What is claimed is :**

- 2 1. A double sided chip package comprising:
- 3 a LOC lead frame having a plurality of leads, wherein each lead being from inside to
- 4 outside divided into a supporting portion, an inner connecting portion and an outer
- 5 connecting portion;
- 6 an upper chip having a plurality of bonding pads on its upper surface and being fixed
- 7 to the top of the supporting portions of the leads with its bottom surface;
- 8 a bottom chip having a plurality of bonding pads and being fixed to the bottom of the
- 9 supporting portions of the leads with its top surface;
- 10 a plurality of bonding wires electrically connecting the bonding pads of the upper
- 11 chip to the inner connecting portions of the corresponding leads, and the bonding
- 12 pads of the bottom chip to the inner connecting portions of the corresponding leads,
- 13 respectively; and
- 14 a package body sealing the upper chip, the bottom chip, the bonding wires, the
- 15 supporting portions and the inner connecting portions of the leads.
- 16 2. The double sided chip package in accordance with claim 1, further comprising a
- 17 plurality of tapes fixing the upper chip and the bottom chip to the supporting portions
- 18 of the leads.
- 19 3. The double sided chip package in accordance with claim 1, further comprising a
- 20 epoxy compound fixing the upper chip and bottom chip on the supporting portions of
- 21 the leads.
- 22 4. The double sided chip package in accordance with claim 1, wherein the supporting
- 23 portions and the inner connecting portions of a plurality of leads are formed on the
- 24 same plane.
- 25 5. The double sided chip package in accordance with claim 4, wherein the supporting
- 26 portions and the inner connecting portions of a plurality of leads are formed on the
- 27 same plane with equal distance to the upper chip and the bottom chip.

1 6. The double sided chip package in accordance with claim 1, wherein the LOC lead  
2 frame additionally includes at least a power lead comprising a supporting portion  
3 sandwiched between the upper chip and the bottom chip, and is perpendicular to the  
4 supporting portions of the other leads.  
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